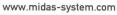
The Development and the commercialization of the Mask Aligner for wafer Midas System will continue to grow along with the value creation for our customers.









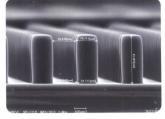
The MDA-60MS offers a higher alignment accuracy and more flexible process of all applications. This is good for piece to 6inch process for research and reliable. This stabilized system will give you a reduction of experimental hours at all times.





▼ SEM Image







ITEM	SPECIFICATIONS	
Substrate Size	Up to 6 inch (option 8 inch)	
UV Lamp Power	1 kW (Option: 350W, 500W)	
Resolution	$0.8 \mu \text{m}$ with $1 \mu \text{m}$ thin PR @ Si wafer	
Alignment Accuracy	$0.5 \mu \mathrm{m}$	
Lamp Uniformity	≤ 3% (6")	
Uniform Beam Size	9.25" × 9.25"	
365nm Beam Intensity	≤25mW/cm²	
Exposure Time	$0.1\sim999.9~{ m sec}$	
Process mode	Vacuum, Hard, Soft and Proximity	
Option	BSA(CCD type), UV-NIL, UV intensity meter	
Dimension	1,400 × 1,100 × 1,600 mm	

